

ABSTRACT OF THE DISCLOSURE

5 A method of machining a glass substrate by-using a
Subal 7 laser, in which a low-permittivity, low-dielectric-loss
glass substrate capable of coping with mass production
processes is made applicable as the substrate of a high-
frequency circuit intended for microwave and millimeter-
10 wave bands in particular. For that purpose, a glass
substrate is provided in which the amount of air bubbles in
glass is arbitrary^{ily} controlled to improve the workability of
the substrate itself. Then, the glass substrate is
machined while being irradiated with a pulsed laser for a
15 plurality of times, thereby improving the machining shape
to the glass substrate. Since glass substrates which are
typically difficult to machine can be easily applied to the
fabrication of high-frequency circuits, it becomes possible
to supply high-performance circuits and apparatuses widely
20 to the public.